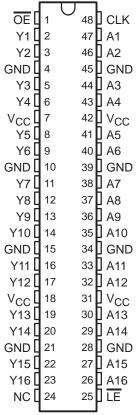
- Member of the Texas Instruments Widebus™ Family
- EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Designed to Comply With JEDEC 168-Pin and 200-Pin SDRAM Buffered DIMM Specification
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

This 16-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (\overline{LE}) input is low. When \overline{LE} is high, the A data is latched if the clock (CLK) input is held at a high or low logic level. If \overline{LE} is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC - No internal connection

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16334 is characterized for operation from -40°C to 85°C.



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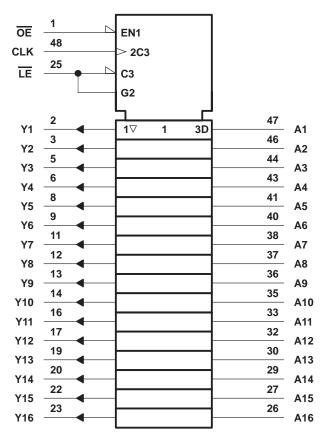


FUNCTION TABLE

	INPUTS						
OE	LE	CLK	Α	Y			
Н	Χ	Х	Χ	Z			
L	L	X	L	L			
L	L	X	Н	Н			
L	Н	\uparrow	L	L			
L	Н	\uparrow	Н	Н			
L	Н	L or H	Χ	Y ₀ †			

[†] Output level before the indicated steady-state input conditions were established

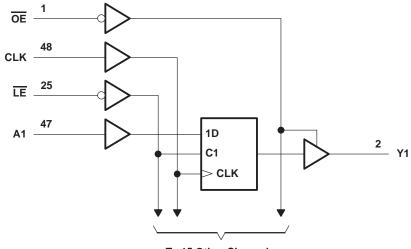
logic symbol‡



[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To 15 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		
Output voltage range, VO (see Notes 1 and 2)		
Input clamp current, I_{IK} ($V_I < 0$)		
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, IO		±50 mA
Continuous current through each V _{CC} or GND		±100 mA
Package thermal impedance, θ _{JA} (see Note 3):	DGG package	89°C/W
	DGV package	93°C/W
	DL package	94°C/W
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



SN74ALVCH16334 16-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS SCES090H - OCTOBER 1996 - REVISED FEBRUARY 1999

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}			
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
٧ı	Input voltage		0	Vcc	V	
٧o	Output voltage		0	Vcc	V	
		V _{CC} = 1.65 V		-4		
1	High lovel output ourrent	V _{CC} = 2.3 V		-12	A	
ЮН	High-level output current	V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
lOL		V _{CC} = 2.3 V		12	A	
	Low-level output current	V _{CC} = 2.7 V		12	mA mA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAME	ETER	TEST C	ONDITIONS	vcc	MIN	TYP†	MAX	UNIT	
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.	.2				
		I _{OH} = -4 mA	1.65 V	1.2					
		I _{OH} = -6 mA	2.3 V	2					
Vон				2.3 V	1.7			V	
		I _{OH} = -12 mA		2.7 V	2.2				
				3 V	2.4				
		I _{OH} = -24 mA		3 V	2				
		I _{OL} = 100 μA		1.65 V to 3.6 V			0.2		
		I _{OL} = 4 mA		1.65 V			0.45		
V		I _{OL} = 6 mA		2.3 V			0.4	V	
VOL		1- 40 m A	2.3 V			0.7	V		
		I _{OL} = 12 mA	2.7 V			0.4			
		I _{OL} = 24 mA	3 V			0.55			
Ц		V _I = V _{CC} or GND		3.6 V			±5	μΑ	
		V _I = 0.58 V		1.65 V	25				
		V _I = 1.07 V	1.65 V	-25					
		V _I = 0.7 V	2.3 V	45					
I _{I(hold)}		V _I = 1.7 V		2.3 V	-45			μΑ	
		V _I = 0.8 V		3 V	75				
		V _I = 2 V	3 V	-75					
		$V_{I} = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$	3.6 V			±500			
loz	$V_O = V_{CC}$ or GND			3.6 V			±10	μΑ	
lCC /		V _I = V _{CC} or GND,	IO = 0	3.6 V			40	μΑ	
ΔlCC		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ	
Con	ntrol inputs	uts		3.3 V		5.5			
C _i Data	a inputs	V _I = V _{CC} or GND	3.3 V	6		pF			
C _O Out	puts	$V_O = V_{CC}$ or GND		3.3 V		8		pF	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

				V _{CC} =	1.8 V	V _{CC} =		VCC =	2.7 V	V _{CC} =		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	f _{clock} Clock frequency			†		150		150		150	MHz	
	Pulse duration			†		3.3		3.3		3.3		20
t _W	Puise duration	CLK high or low		†		3.3		3.3		3.3		ns
		Data before CLK↑		†		1.4		1.7		1.5		
t _{su}	Setup time	Bata hatana IEA	CLK high	†		1.2		1.6		1.3		ns
		Data before LE↑	CLK low	†		1.4		1.5		1.2		
		Data after CLK↑		†		0.9		0.8		0.9		
th	Hold time	Data after LE↑	CLK high or low	†		1.2		1.1	·	1.1		ns

[†] This information was not available at the time of publication.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC =	1.8 V	VCC =	2.5 V 2 V	VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(IIVFO1)	(0011-01)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		150		150		150		MHz
	А			†	1	3.7		3.6	1.1	3.3	
t _{pd}	LE	Y		†	1	4.8		5	1.3	4.4	ns
	CLK			†	1	4.4		4.5	1	4.1	
t _{en}	ŌĒ	Y		†	1	5.4		5.4	1.1	4.6	ns
^t dis	ŌĒ	Y		†	1	4.1		4.5	1.7	4.4	ns

[†] This information was not available at the time of publication.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT		
		TEST CONDITIONS	TYP	TYP	TYP			
C .	Power dissipation	Outputs enabled	C ₁ = 0. f = 10 MHz	†	32	37	pF	
Cpd	capacitance	Outputs disabled	$C_L = 0$, $f = 10 \text{ MHz}$	†	7	11	pr	

[†]This information was not available at the time of publication.

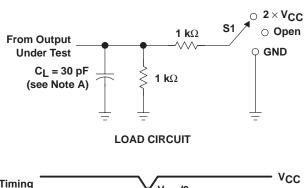


VCC

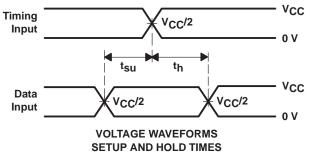
0 V

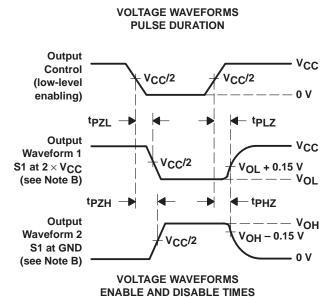
V_{CC}/2

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V}$



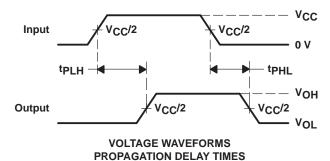
TEST	S1
t _{pd}	Open
tpLz/tpzL	2×V _{CC}
tpHz/tpzH	GND





V_{CC}/2

Input

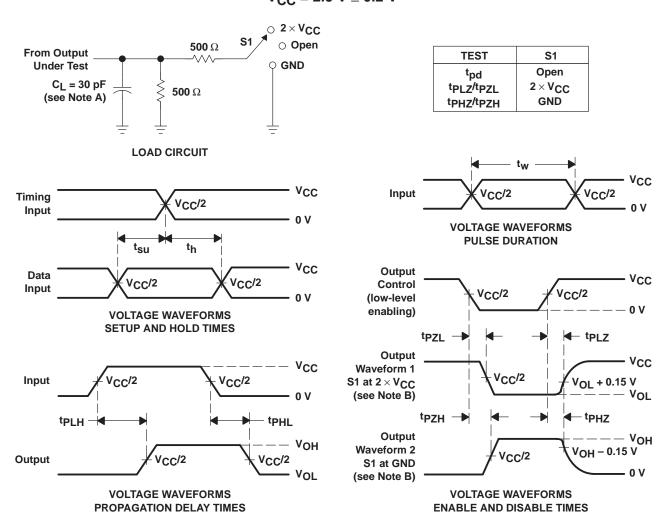


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$



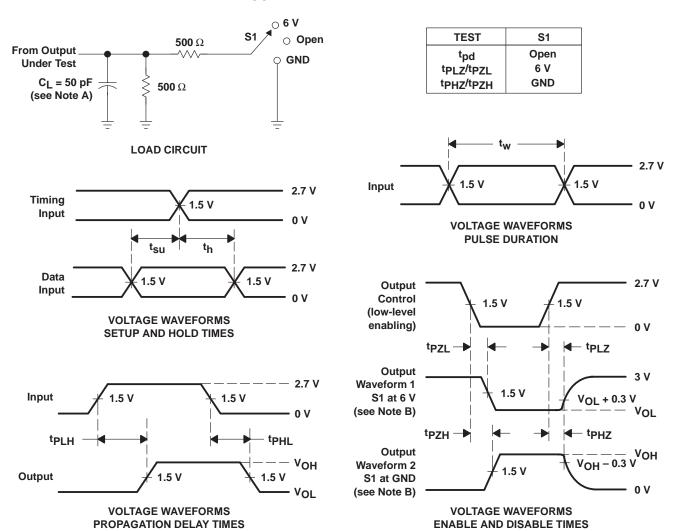
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \,\Omega$, $t_{r} \leq 2.5 \,\text{ns}$, $t_{f} \leq 2.5 \,\text{ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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